

D1: Advanced Packaging, Interfacing, and System Integration	
Location: Conference Room 103A, 1F	
November 2, 2026	
Presider: Lei Ting, Shenzhen University Session: CPO and Optical Interconnects	
13:15-13:45	1.6Tbps optical engine for co-packaged optics systems (Invited) Bigeng Chen Zhejiang Lab, China
13:45-14:15	Ultra-High-Density Silicon Photonic Interconnects for AI Computing Clusters (Invited) Binhao Wang 1. Xi'an Institute of Optics and Precision Mechanics, Chinese Academy of Sciences, China; 2. Beijing Lingxi Photonix Technology Co., Ltd., China
14:15-14:45	Advanced optical interconnection for I/O in AI Compute Infrastructure (Invited) Yuan Li Zhangjiang Laboratory, China
14:45-15:15	AI-Driven Multidimensional Silicon Photonics Devices and Intelligent Photonic Processors (Invited) Yeyu Tong Hong Kong University of Science and Technology (Guangzhou), China
15:15-15:30	Ultra-Low-Loss Fusion Splicing of Anti-Resonant Hollow-Core Fiber Enabled by Dual-Beam CO₂ Laser Processing (Oral) Haojie Chen MIIT Key Laboratory of Aerospace Information Materials and Physics, College of Physics, Nanjing University of Aeronautics and Astronautics, China
15:30-16:00	Coffee Break
Presider: Shaoliang Yu, Zhejiang Lab Session: Optical Coupling and Packaging	
16:00-16:30	Advanced Waveguide Grating Couplers for high bandwidth-density applications (Invited) Hon Ki Tsang The Chinese University of Hong Kong, China
16:30-17:00	Glass-based 3D waveguides for high-density optical packaging (Invited) Lei Ting Shenzhen University, China
17:00-17:15	Sub-dB Polymer-to-Silicon Photonic Adiabatic Coupler Enabled by a SiN Interlayer (Oral) TOON DE BAERE UGent, Belgium
17:15-17:30	Low-Divergence Tri-Tip Inverse-Taper Silicon End-Fire Emitter for Broadband Free-Space Emission (Oral) Yicheng Wang Southern University of Science and Technology, China

17:30-17:45	Silicon Polarization Controller with Integrated End-Fire Emitter for Tunable Linearly Polarized Output (Oral) Yicheng Wang Southern University of Science and Technology, China
-------------	--

D1: Advanced Packaging, Interfacing, and System Integration	
Location: Conference Room 103A, 1F	
November 3, 2026	
Presider: Jiawei Wang, Harbin Institute of Technology (Shenzhen) Session: Optical Beam Manipulation	
08:30-09:00	Integrated optical phased array for optical wireless communications (Invited) Hao Hu Technical University of Denmark, Denmark
09:00-09:30	TBD (Invited) Ke Xu Harbin Institute of Technology (Shenzhen), China
09:30-09:45	Metasurface Photonic-crystal Multivariate Optical Elements with Integrated Metalenses (Oral) Pengjiu Zhao Shanghai Jiao Tong University, China
09:45-10:00	Optical Path Scaling via Multimode Recirculation (Oral) Xiyue Lyu Fudan University, China
10:00-10:30	Coffee Break
Presider: Hao Hu, Technical University of Denmark Session: Emerging Materials for Photonic Integration	
10:30-11:00	Hybrid-Integrated TFLN-Based Coherent Optical Sub-Assembly Enabling 128Gbaud DP-16QAM 800Gps/λ Transmission (Invited) Keqi Cao Institute of Semiconductor, Chinese Academy of Sciences, China
11:00-11:30	Ferroelectric optical memristors (Invited) Yang Zhang Nankai University, China
11:30-12:00	Wafer level heterogeneous co-packaging optoelectronics for ultrabroadband microsystems (Invited) Liang Zhou Shanghai Jiao Tong University, China
12:00-12:15	Fabrication-Friendly PZT First-Order Bragg Topological Slow-Light Waveguide for Compact Electro-Optic Phase Modulation (Oral) Jing He Nankai University, China